

HDB108LS -

SURFACE MOUNT GLASS PASSIVATED HIGH EFFICIENCY SILICON RECTIFIER **VOLTAGE 1000 Volts CURRENT 1.0 Ampere**

FEATURES

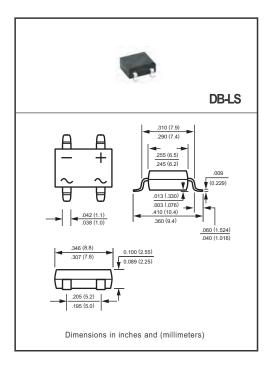
- * Glass passivated device
- * Good for automation insertion
- * Low leakage current
- * Ideal for printed circuit board
- * Polarity symbols molded on body
- * Mounting position: Any
- * Weight: 0.335 gram

MECHANICAL DATA

* Epoxy: Device has UL flammability classification 94V-O

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. resistive or inductive load.



MAXIMUM RATINGS (@ TA=25 °C unless otherwise noted)

RATINGS	SYMBOL	HDB108LS	UNITS
Maximum Recurrent Peak Reverse Voltage		1000	Volts
Maximum RMS Voltage		700	Volts
Maximum DC Blocking Voltage	V _{DC}	1000	Volts
Maximum Average Forward Rectified Current at T _A = 50°C	Io	1.0	Amps
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	30	Amps
Current Squarad Time	l ² t	3.7	A ² /Sec
Typical Thermal Resistance (Note 1)	Røjl	27	°C/W
Typical Thermal Resistance (Note 1)	R _{θJA}	75	°C/W
Typical Junction Capacitance (Note 2)	CJ	12	pF
Operating Temperature Range	TJ	150	٥C
Storage Temperature Range	T _{STG}	-55 to + 150	°C

ELECTRICAL CHARACTERISTICS(@TA=25 °C unless otherwise noted)

CHARACTERI	STICS	SYMBOL	HDB108LS	UNITS
Maximum Instantaneous Forward Voltag	e at 1.0A DC	V _F	1.7	Volts
Maximum Full Load Reverse Current, Full cycle Average T _A =55°C		I-	50	
Maximum Average Reverse Current	@T _A = 25°C	IR I	5	uА
at Rated DC Blocking Voltage	@T _A = 125°C		100	uА
Maximum Reverse Recovery Time (Note 4)		trr	75	nSec

NOTES: 1. Thermal Resistance: Mounted on PCB.

- 2. Measured at 1 MHz and applied reverse voltage of 4.0 volts.

 3. "Fully ROHS compliant", "100% Sn plating (Pb-free)".

 4. Test Conditions: I_F= 0.5A, I_R= -1.0A, I_{RR}= -0.25A.

2015-04 REV: O

RATING AND CHARACTERISTICS CURVES (HDB108LS)

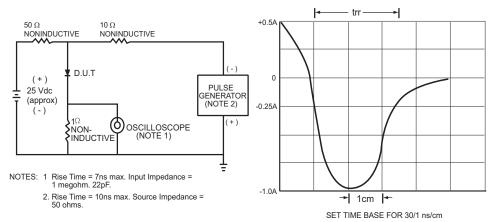
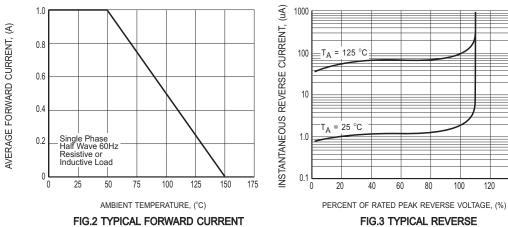


FIG.1 TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



DERATING CURVE

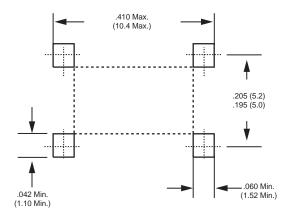
80

120

140

60

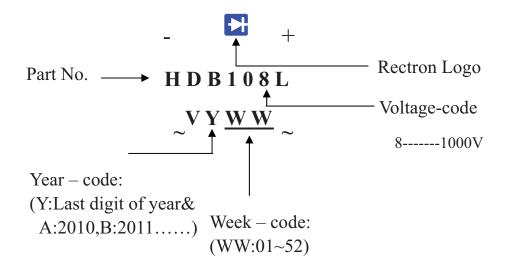
Mounting Pad Layout



Dimensions in inches and (millimeters)



Marking Description



PACKAGING OF DIODE AND BRIDGE RECTIFIERS

REEL PACK

PACKAGE	PACKING CODE	EA PER REEL	EA PER INNER BOX	COMPONENT SPACE (mm)	TAPE SPACE (mm)	REEL DIA (mm)	CARTON SIZE (mm)	EA PER CARTON	GROSS WEIGHT(Kg)
DB-LS	-T/W	1,000	1,000	9.5	52	330	360*355*360	8,000	9.5



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